



100% Material Declaration Data Sheet HQ240

PK163 (v1.2) October 3, 2006

Material Declaration Data Sheet

Average Weight: 15.35571 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.22748	1.48%
	Silicon	7440-21-3	100.00		0.22748	
Die Attach Material					0.01916	0.12%
	Silver	7440-22-4	75.00		0.014368	
	Epoxy (EP)	Trade Secret	25.00		0.004789	
Mold Compound					3.96134	25.80%
	Epoxy Resin (EP)	Trade Secret	16.00		0.633815	
	Silica	60676-86-0	84.00		3.327527	
Leadframe					0.53985	3.52%
	Copper	7440-50-8	99.25		0.535804	
	Chromium	7440-47-3	0.30		0.001620	
	Tin	7440-31-5	0.25		0.001350	
	Zinc	7440-66-6	0.20		0.001080	
Leadframe Plating					0.00161	0.01%
	Silver	7440-22-4	100.00		0.00161	
Heat Slug					10.54917	68.70%
	Copper	7429-50-8	100.00		10.54917	
Ext. Heat Sink plating					0.00706	0.05%
	Nickel	7440-02-0	100.00		0.00706	
Bond Wire					0.00826	0.05%
	Gold	7440-57-5	100.00		0.00826	
Ext. Plating					0.04178	0.27
	Tin	7440-31-5	85.00		0.035513	
	Lead	7439-92-1	15.00		0.006267	

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/23/06	1.0	Initial release.
7/05/06	1.1	100% Material Declaration.
10/3/06	1.2	Updated component descriptions.